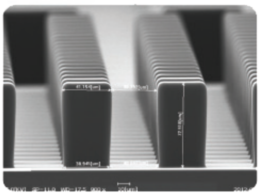
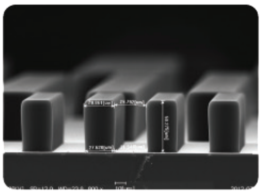
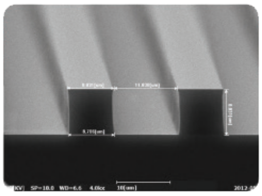
4" MANUAL MASK ALIGNER

Our manual control MDA-400M series standard feature UV Light source 350 nm to 450 nm, 365 nm Intensity: 20-30 mW/cm^2 and a beam size of 6.25" x 6.25" (3 % beam uniformity for 4" wafers) and automatic exposure system. The unit comes with a Dual CCD zoom microscope with 19" LCD monitor: magnification; 5X-20X digital CCD.

Contact modes include Soft, Vacuum Hard and Proximity. The Vacuum and Hard Contact are adjustable with an alignment accuracy of <1.0 micron.







OPTIONS

- Anti-Vibration table
- UV Intensity Meter
- UV-LED (365 nm) Exposure Module

Configuration

Substrate size	Up to 4" also available for 6"
Light source	350 W
Resolution	1 µm with 1 µm thin PR @ Si Wafer
Alignment accuracy	± 1 µm
365nm beam intensity	> max. 30 mW/cm^2
Process mode	Soft, Hard, Vacuum contact & Proximity